



Product Change Notification

Change Notification #: 116667 - 00
Change Title: Intel® RAID Module RMSP3HD080E, PCN 116667-00, Product Design, Resistor Change and Firmware Update
Date of Publication: December 18, 2018

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material: *	January 2, 2019
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*Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing the following changes on the Intel® RAID Module RMSP3HD080E listed in the products affected table below.

1. Change in resistor placement in the memory voltage regulator circuit order to allow 1.8V NOR flash memory. This is to allow a second source memory vendor.
2. Remove R46 and R51 resistors in order to fix the global activity LED issue.
3. Update the firmware to version 5.050.00-1367 (MR 7.5p2 on firmware package 50.5.2-1326)

Customer Impact of Change and Recommended Action:

Intel does not expect any other impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications. For that reason Intel recommends that the customer perform a standard level of evaluation. Customers can download and evaluate the latest BIOS/ME/Integrated BMC and FRUSDR release notes for more information at

<http://www.intel.com/support>.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
RMSP3HD080E	954553	J32824-004	J32825-202	J32824-005	J32825-203

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
December 18, 2018	00	Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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